



# CED01N65/CEU01N65

## N-Channel Enhancement Mode Field Effect Transistor

PRELIMINARY

### FEATURES

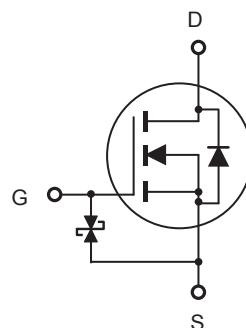
- 650V, 1.2A,  $R_{DS(ON)} = 10.5\Omega$  @ $V_{GS} = 10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead free product is acquired.
- TO-251 & TO-252 package.



CEU SERIES  
TO-252(D-PAK)



CED SERIES  
TO-251(I-PAK)



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous	$I_D$	1.2	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	4.8	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	$P_D$	35.7 0.29	W W/ $^\circ C$
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{JC}$	3.5	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{JA}$	50	$^\circ C/W$

[www.DataSheet4U.com](http://www.DataSheet4U.com)

This is preliminary information on a new product in development now .  
Details are subject to change without notice .

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<http://www.cetsemi.com>



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## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

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Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$			25	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			10	$\text{uA}$
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-10	$\text{uA}$
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.6\text{A}$		8.5	10.5	$\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 10\text{V}, I_D = 0.6\text{A}$		1		S
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		215		pF
Output Capacitance	$C_{\text{oss}}$			50		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			20		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 300\text{V}, I_D = 1.2\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 4.7\Omega$		14.3	38.6	ns
Turn-On Rise Time	$t_r$			14.6	29.2	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			23	46	ns
Turn-Off Fall Time	$t_f$			17	34	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 480\text{V}, I_D = 1.2\text{A}, V_{\text{GS}} = 10\text{V}$		5.8	11.6	nC
Gate-Source Charge	$Q_{\text{gs}}$			1.9		nC
Gate-Drain Charge	$Q_{\text{gd}}$			2.4		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				1.2	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 0.6\text{A}$			1.5	V

## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature..□
- b.Device Mounted on FR4 Board,  $t < 10 \text{ sec.}$  □
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .□
- d.Guaranteed by design, not subject to production testing.□



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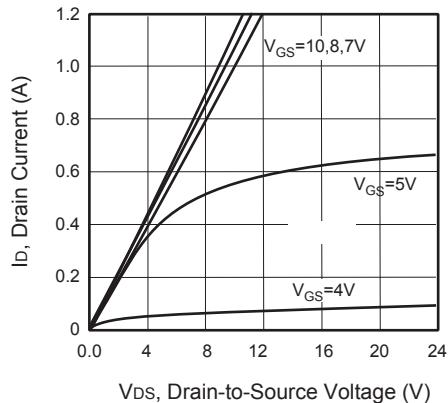


Figure 1. Output Characteristics

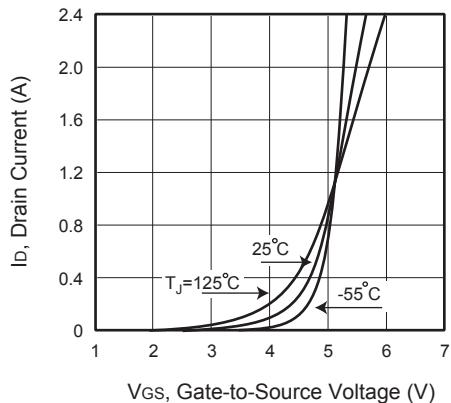


Figure 2. Transfer Characteristics

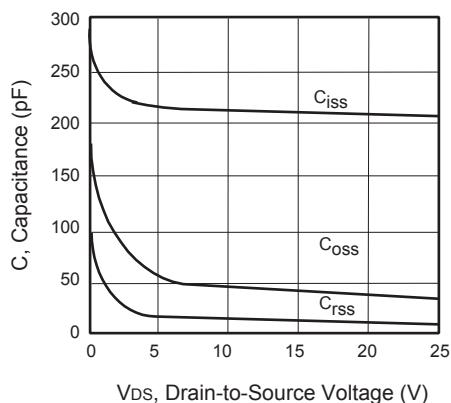


Figure 3. Capacitance

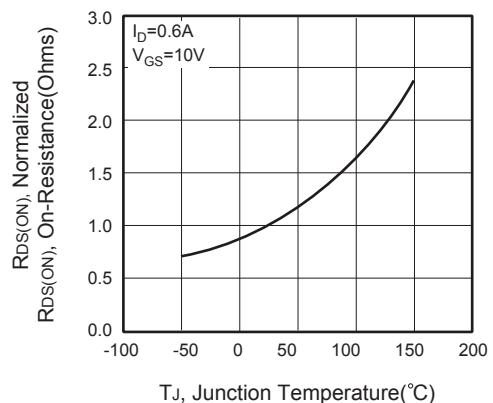


Figure 4. On-Resistance Variation with Temperature

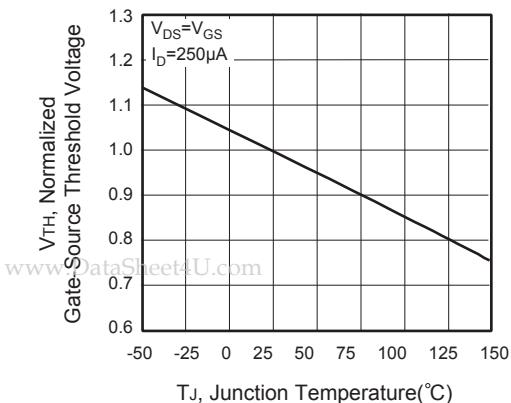


Figure 5. Gate Threshold Variation with Temperature

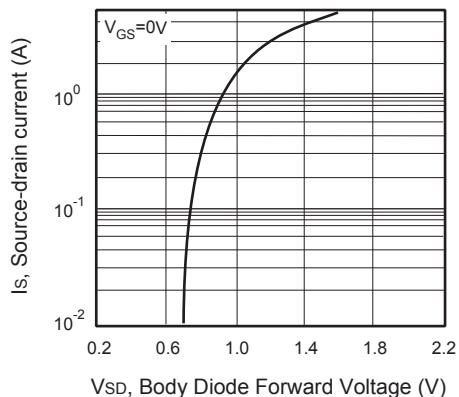


Figure 6. Body Diode Forward Voltage Variation with Source Current

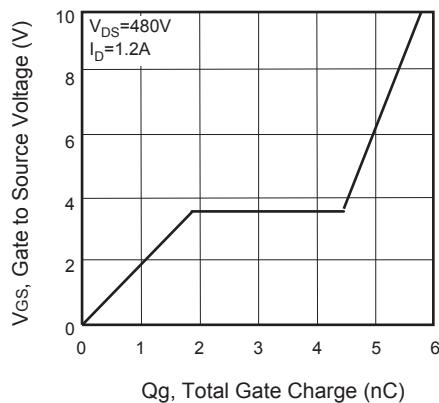


Figure 7. Gate Charge

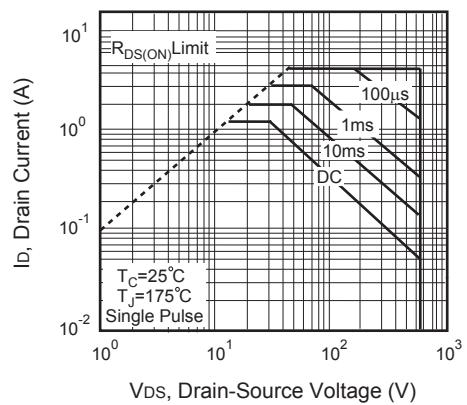


Figure 8. Maximum Safe Operating Area

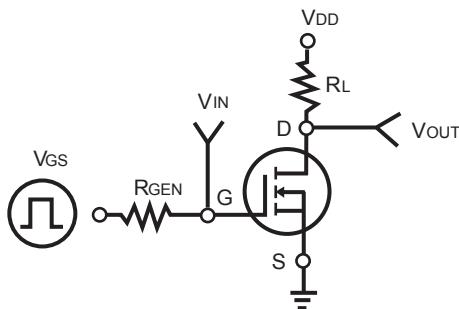


Figure 9. Switching Test Circuit

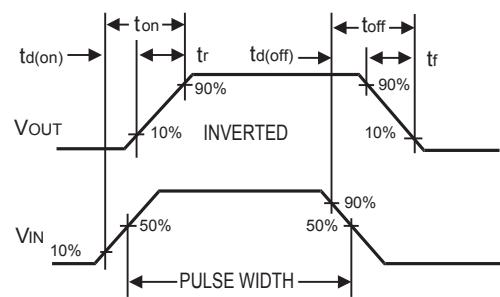


Figure 10. Switching Waveforms

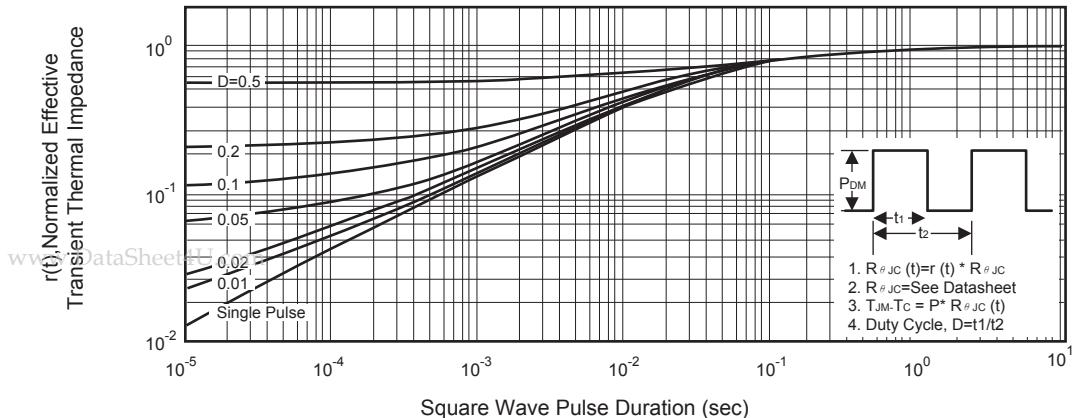


Figure 11. Normalized Thermal Transient Impedance Curve